

Inductorless -2x Boost/Buck Regulator

Features

- Input Range 2.5V to 5.5V
- Regulated Output Options from -3.0 to -5.0V
- Output Current 20mA (max)
- 200kHz Internal Oscillator Frequency
- External Synchronizing Clock Input
- Logic Level Shutdown
 - 1 μ A (max) Supply Current
- Available in 8-Pin MSOP Package

Applications

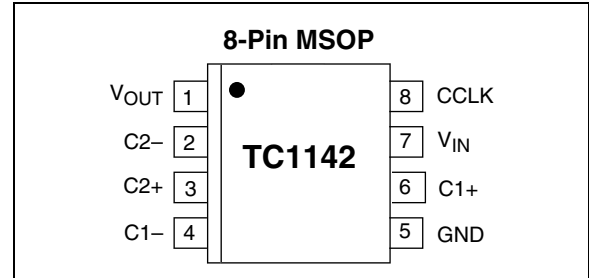
- Cellular Phones
- Battery Powered/Portable Equipment

Device Selection Table

Part Number	Output Voltage (V)*	Package	Operating Temp. Range
TC1142-3.0EUA	3.0	8-Pin MSOP	-40°C to +85°C
TC1142-4.0EUA	4.0	8-Pin MSOP	-40°C to +85°C
TC1142-5.0EUA	5.0	8-Pin MSOP	-40°C to +85°C

*Other output voltages are available (-3.5V and -4.5V). Please contact Microchip Technology Inc. for details.

Package Type



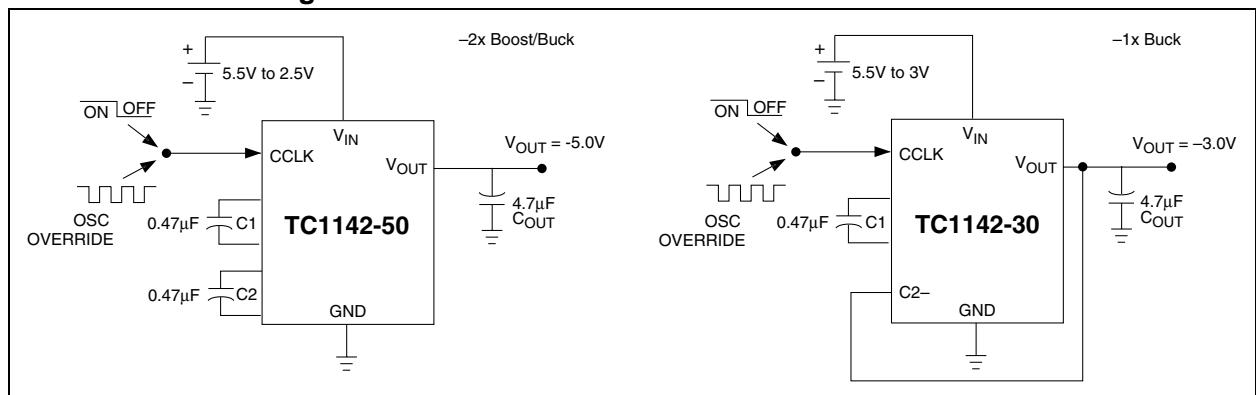
General Description

The TC1142 generates a regulated negative voltage from -3V to -5V at 20mA from an input of 2.5V to 5.5V, using only three external capacitors. Other boost/buck switching regulators must use an inductor, which is larger and radiates EMI. An internal voltage comparator inhibits the charge pump when V_{OUT} is more negative than the regulated value (per the ordering option). The values of flying capacitors C1 and C2 are chosen to be less than C_{OUT} in order to reduce the ripple generated from regulating V_{OUT} in this manner. The TC1142 also can be used as a -1x buck regulator by omitting C2, and connecting the C2 pin to V_{OUT} .

The part goes into shutdown when the CCLK input is driven low. When in shutdown mode, the part draws a maximum of 1 μ A. When CCLK is pulled high, the part runs from the internal 200kHz oscillator. The device may be run with an external clock, provided the frequency is greater than 3kHz and less than 500kHz.

The TC1142 comes in a space-saving MSOP package.

Functional Block Diagram



TC1142

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage (V_{IN}) with C_{OUT} Connected 6.5V
 CCLK Voltage -0.3V to ($V^+ + 0.3V$)
 Power Dissipation 320mW
 Operating Temperature Range
 8-Pin MSOP -40°C to +85°C
 Storage Temperature Range -65°C to +160°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC1142 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $R_L = \infty$, $V_{IN} = 3.2V$, Mode = -2x, $C_1 = C_2 = 0.47\mu F$ (Note 1), $CCLK = V_{IH}$, $C_{OUT} = 4.7\mu F$, for $V_R = 3V$, $V_{IN} = 3.5V$, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.

Symbol	Parameter	Min	Typ	Max	Units	Test Conditions
V_{IN}	Supply Voltage	2.5	—	5.5	V	
V_{OUT}	Output Voltage	$-(V_R + 0.2)$	$-V_R$	$-(V_R - 0.2)$	V	$I_L = 0mA$ (Note 2)
V_{P-P}	Output Ripple	—	100	—	mV	$I_L = 10mA$
I_{SUPPLY}	Supply Current	—	200	400	μA	
$I_{SUPPLY1}$		—	0.1	1	μA	CCLK = 0V
R_{OUTCL}	Closed-Loop Output Resistance	—	2	6	Ω	
R_{OUT}	Open-Loop Output Resistance	—	30	—	Ω	(Note 3)
f_{OSC}	Internal Oscillator Frequency	150	200	275	kHz	
f_{CCLK}	External Clock Frequency, Typical	3	—	500	kHz	(Note 4)
P_{EFF}	Power Efficiency	70	76	—	%	$I_L = 10mA$, $V_R = 5V$; (See Equation 3-5)
V_{IH}	CCLK Input High Threshold	2.2	—	—	V	
V_{IL}	CCLK Input Low Threshold	—	—	1.0	V	

- Note**
- 1: Assume C_1 and C_2 have an ESR of 1Ω .
 - 2: V_R is the voltage output specified in the ordering option.
 - 3: Measured in -1x Mode. For $V_R = 3V$, $V_{IN} = 2.5V$.
 - 4: CCLK is driven with an external clock. Minimum frequency = $1/2t_0$ at 50% duty cycle, where t_0 is the counter timeout period.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin No. (8-Pin MSOP)	Symbol	Description
1	V_{OUT}	Regulated negative output voltage.
2	C2-	Negative terminal of flying capacitor C2.
3	C2+	Positive terminal of flying capacitor C2.
4	C1-	Negative terminal of flying capacitor C1.
5	GND	Power supply ground.
6	C1+	Positive terminal of flying capacitor C1.
7	V_{IN}	Power supply positive voltage input (2.5V to 5.5V).
8	CCLK	Clock control input: If low, the TC1142 is in Shutdown mode (1 μ A, max). If high, the TC1142 runs off the internal oscillator (200kHz, typ.). CCLK can be overridden by an external oscillator from 3kHz to 500kHz.

FIGURE 3-2: TC1142 PHASE 1

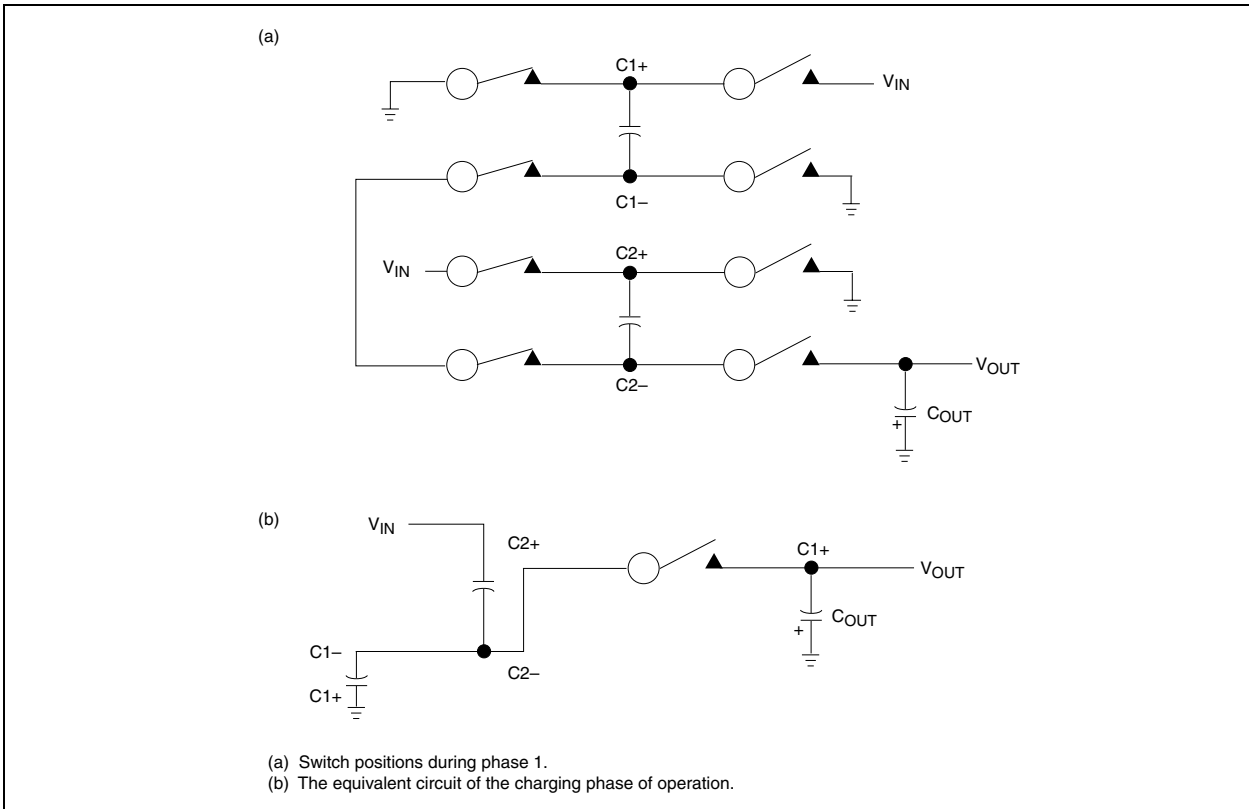
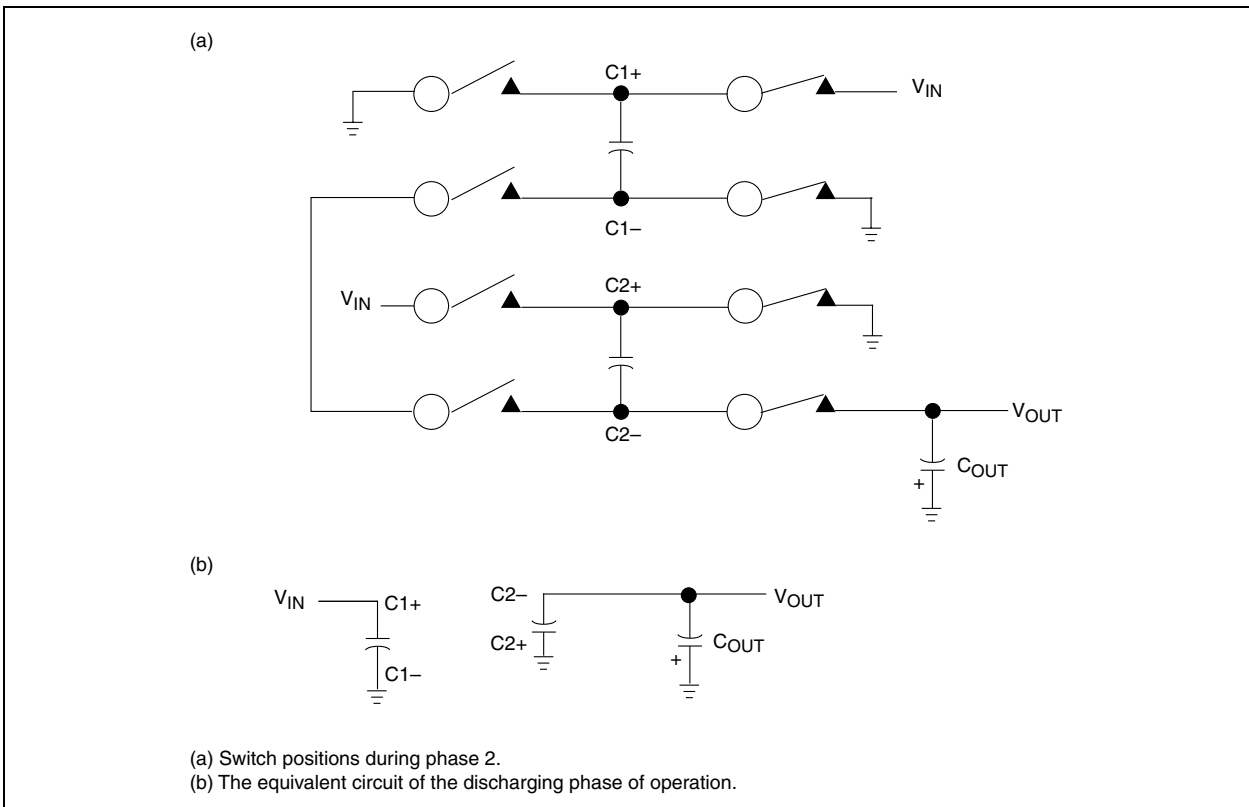


FIGURE 3-3: TC1142 PHASE 2



TC1142

3.1 Output Voltage and Ripple

For a -2x boost:

a.) For unregulated operation when $V_{IN} \leq \left| \frac{V_R}{2} \right|$.

In this case, the output voltage is given by:

EQUATION 3-1:

$$V_{OUT} = -|2V_{IN}| + I_O R_{OUT}$$

$$\text{where } R_{OUT} = \frac{1}{f} \left(\frac{1}{C_1} + \frac{1}{C_2} \right) + \frac{R_S C_2}{(C_2 + C_{OUT})}$$

Here, f is the clock frequency and R_S is the total ON resistance of the switches connecting C_2 to GND and V_{OUT} in phase 2 of the charge pump operating cycle with the equivalent series resistance (ESR) of C_2 .

The output ripple voltage is given by:

EQUATION 3-2:

$$V_{RIPPLE} = I_O R_{RIPPLE}$$

$$\text{where } R_{RIPPLE} = \frac{1}{2f(C_2 + C_{OUT})} + \frac{1}{2fC_{OUT}} + \frac{ESR C_2}{(C_2 + C_{OUT})}$$

Here, ESR is the equivalent series resistance of C_{OUT} .

b.) For regulated operation when $V_{IN} > \left| \frac{V_R}{2} \right|$.

In this case, the TC1142 is held in phase 2 until the output voltage drops below V_R . When this occurs, the TC1142 reverts to phase 1 for a half period of the clock, during which C_2 is charged from C_1 . At the end of this half-period, C_2 is reconnected to C_{OUT} to boost the output voltage. During the phase 1 time period, the output voltage will drop below V_R before it is boosted back, so the minimum output voltage is approximated by:

EQUATION 3-3:

$$V_{OUTMIN} = -|V_R| + I_O R_{OUT}$$

$$\text{where } R_{OUT} = \frac{1}{2fC_{OUT}} + \frac{ESR C_2}{(C_2 + C_{OUT})}$$

The output ripple voltage is given approximately by:

EQUATION 3-4:

$$V_{RIPPLE} = \frac{(2V_{IN} - |V_R| + ESR I_O C_2 \left(\frac{1}{C_1} + \frac{1}{C_2} \right))}{N}$$

$$\text{where } N = \left(\frac{1}{C_1} + \frac{1}{C_2} \right) (C_2 + C_{OUT})$$

For values of V_{IN} higher than $|V_R/2|$ by several hundred mV, the effect on ripple of the ESR of C_{OUT} can be neglected compared to the "overdrive" effect of V_{IN} .

Here, it can be seen that V_{RIPPLE} increases with increasing V_{IN} , but can be minimized by choosing small C_1 and C_2 values and a large C_{OUT} value.

3.2 Capacitor Selection

To maintain low output impedance and ripple, it is recommended that capacitors with low equivalent series resistance (ESR) be used. Additionally, larger values of the output capacitor and smaller values of the flying capacitors will reduce output ripple. For a capacitor value of $4.7\mu\text{F}$ for C_{OUT} , and values of $0.47\mu\text{F}$ for C_1 and C_2 , the typical output impedance of the TC1142 in regulation is 0.5Ω . For the capacitor ESR not to have a noticeable effect on output impedance, it should not be larger than $1/2fC_{OUT}$. This also makes its effect on ripple voltage negligible. For $V_{IN} = 3.2\text{V}$ and $V_R = -5\text{V}$, the output ripple voltage is less than 70mV_{PP} . Table 3-1 summarizes output ripple versus capacitor size for an input voltage of 3.2V and a regulated output voltage of -5V .

Surface mount ceramic capacitors are preferred for their small size, low cost and low ESR. Low ESR tantalum capacitors also are acceptable. See Table 3-2 for a list of suggested capacitor suppliers.

TABLE 3-1: VOLTAGE RIPPLE VS. C1/C2 FLYING CAPACITORS AND OUTPUT CAPACITOR C_{OUT} ESR = 0.1Ω , $I_{OUT} = 20\text{mA}$

C1, C2 (μF)	C_{OUT} (μF)	V_{IN} (V)	V_{OUT} (V)	V_{RIPPLE} (mV)
0.1	4.7	3.2	-5	14.6
0.22	4.7	3.2	-5	31.4
0.33	4.7	3.2	-5	46.1
0.47	4.7	3.2	-5	63.9
0.68	4.7	3.2	-5	88.7
1.0	4.7	3.2	-5	123.2
0.1	10	3.2	-5	7.0
0.22	10	3.2	-5	15.1
0.33	10	3.2	-5	22.4
0.47	10	3.2	-5	31.5
0.68	10	3.2	-5	44.7
1.0	10	3.2	-5	63.8

TABLE 3-2: LOW ESR SURFACE-MOUNT CAPACITOR MANUFACTURERS

Manufacturer	Type	Phone
AVX Corp.	TPS series surface-mount tantalum X7R type surface-mount ceramic	803-448-9411
Matsuo	267 series surface-mount tantalum X7R type surface-mount ceramic	714-969-2491
Sprague	593D, 594D, 595D series surface-mount tantalum	207-324-4140
Murata	Ceramic chip capacitors	800-831-9172
Taiyo Yuden	Ceramic chip capacitors	800-348-2496
Token	Ceramic chip capacitors	408-432-8020

3.3 Power Efficiency

Assuming the output is loaded with at least 20% of the maximum available output current, the power efficiency of the TC1142 can be estimated using the following equation:

EQUATION 3-5:

$$\eta = \frac{|V_R|}{2(V_{IN})}$$

For example, a 3.2 Volt V_{IN} , and a -5 Volt V_R will have an efficiency of approximately 78%. For loads less than 20% of the maximum available output current, the power efficiency will be substantially reduced. Other factors that affect the actual efficiency include:

1. Losses from power consumed by the internal oscillator (if used).
2. I^2R losses due to the on-resistance of the MOSFET charge pump switches.
3. Charge pump capacitor losses due to ESR.
4. Losses that occur during charge transfer (from the flying capacitors to the output capacitor) when a voltage difference exists between these capacitors.

3.4 Choice of -2x or -1x Connections

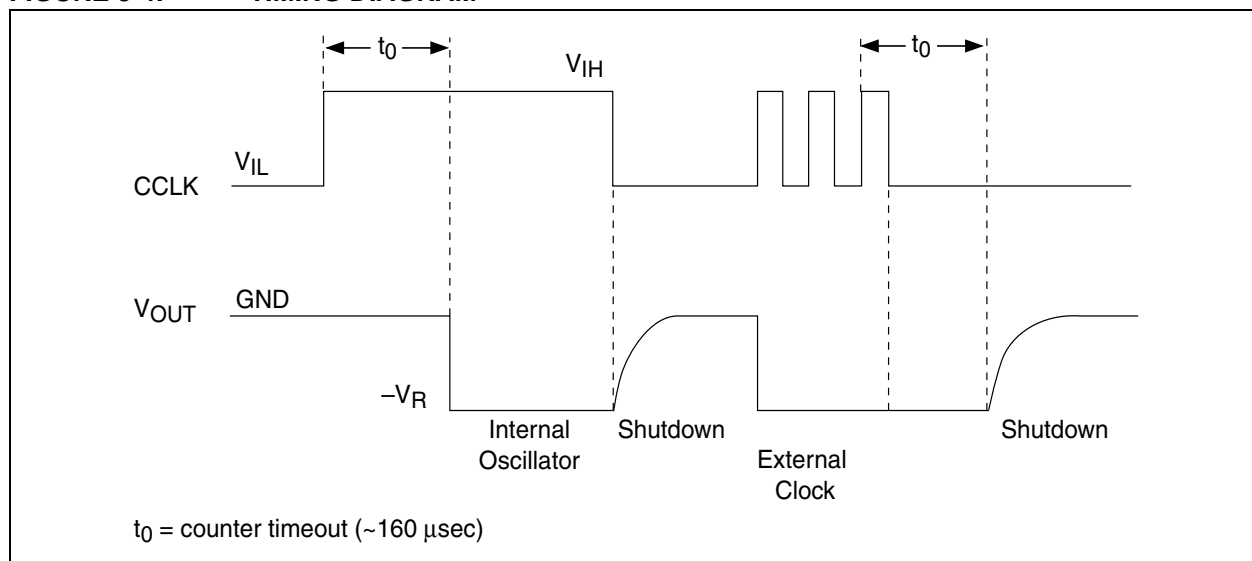
If required output voltage can be achieved using a -1x configuration then this is preferred for the following reasons:

1. Power efficiency is improved from $V_R/2V_{IN}$ to V_R/V_{IN}
2. Only one flying capacitor needed
3. The output ripple becomes proportional to $V_{IN} - V_R$ rather than $2V_{IN} - V_R$.

3.5 Layout Considerations

Proper layout is important to obtain optimal performance. Mount capacitors as close to their connecting device pins as possible to minimize stray inductance and capacitance. It is recommended that a large ground plane be used to reduce noise leakage into other circuitry.

FIGURE 3-4: TIMING DIAGRAM



TC1142

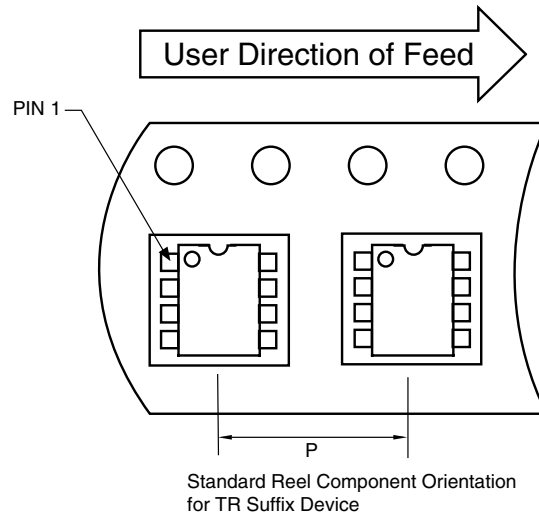
4.0 PACKAGING INFORMATION

4.1 Package Marking Information

Package marking data not available at this time.

4.2 Taping Form

Component Taping Orientation for 8-Pin MSOP Devices

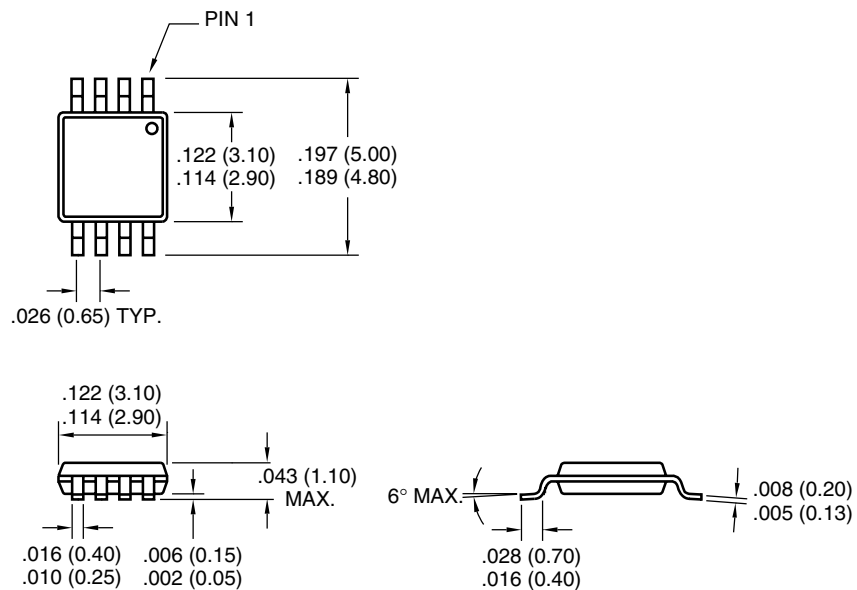


Carrier Tape, Number of Components Per Reel and Reel Size

Package	Carrier Width (W)	Pitch (P)	Part Per Full Reel	Reel Size
8-Pin MSOP	12 mm	8 mm	2500	13 in

4.3 Package Dimensions

8-Pin MSOP



Dimensions: inches (mm)

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Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

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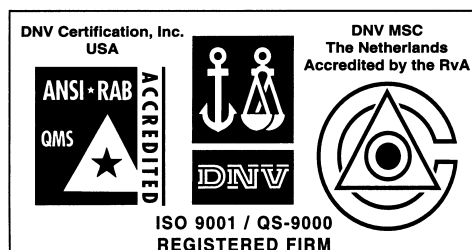
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